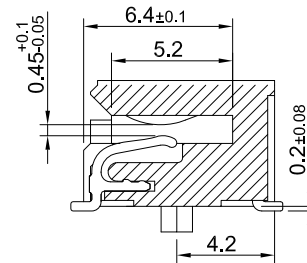
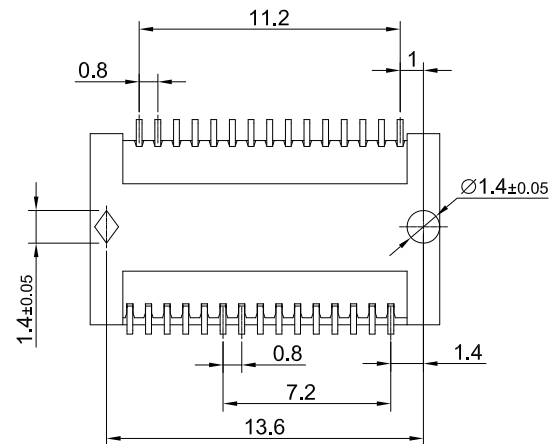
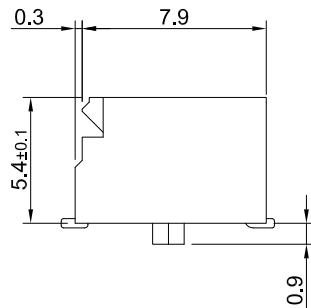
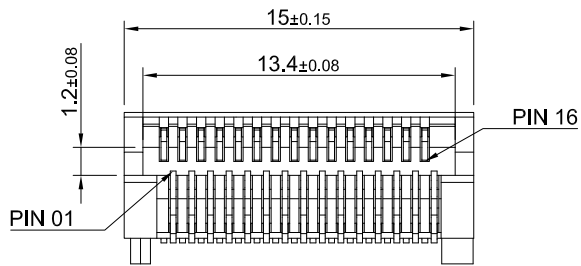


**MATERIAL**  
 CONTACTS: COPPER ALLOY  
 INSULATOR: LCP THERMOPLASTIC 94V-0

**FINISH**  
 CONTACT: 15 μ" MIN. GOLD ON MATING END;  
 MATTE TIN ON TERMINATION END;  
 ALL UNDERPLATED NICKEL

**ELECTRICAL CHARACTERISTICS**  
 CONTACT RESISTANCE: 35 MILLOHMS MAX.  
 DIELECTRIC WITHSTANDING VOLTAGE: 300 VAC

**ENVIRONMENT**  
 OPERATION TEMPERATURE: -55°C TO +85°C

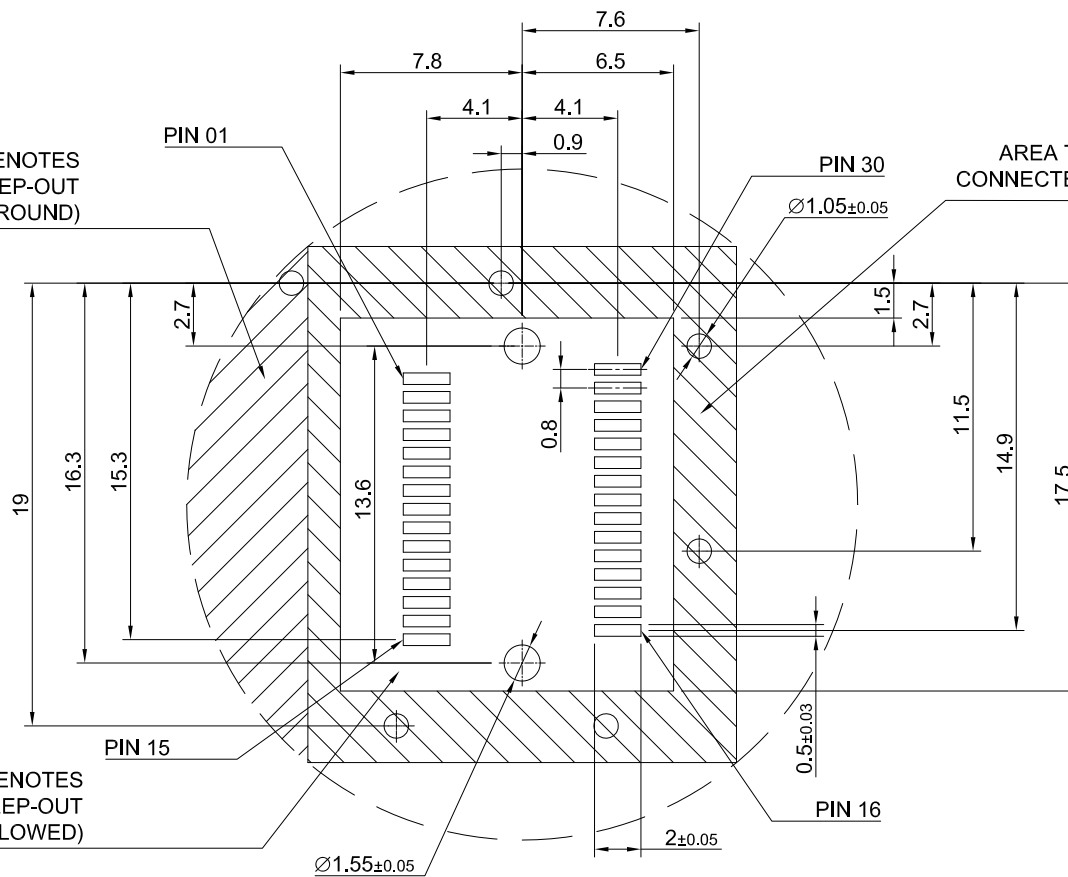


<b>TITLE:</b> XFP 30Pin PCB Connector			
<b>DWG#:</b> R-SS-008030-3-N		<b>SHEET:</b> 1/2	<b>REV.:</b> E
<b>UNIT:</b> mm	<b>SCALE:</b> A4 3:1	<b>FINISH:</b>	<b>CHECKED:</b> Gary Kang
<b>THIRD ANGLE PROJECTION</b>		<b>MATERIAL:</b> RoHS Compliant	<b>APPROVED:</b> George Yang
<b>TOLERANCE:</b> Angle: ± 1° X, ± 0.25 .X ± 0.20 .XX ± 0.15		<b>DRAWN:</b> Sheng	<b>DATE:</b> 09/10/2014

CROSS HATCHED AREA DENOTES  
COMPONENT AND TRACE KEEP-OUT  
(EXCEPT CHASSIS GROUND)

AREA TO BE CONDUCTIVE AND  
CONNECTED TO CHASSIS GROUND

THIS AREA DENOTES  
COMPONENT KEEP-OUT  
(TRACES ALLOWED)



30 CIRCUIT MOTHER BOARD  
RECOMMENED PCB LAYOUT  
TOLERANCE:±0.05



ALL BEST  
ELECTRONICS  
CO., LTD.

TITLE: XFP 30Pin PCB Connector

DWG#: R-SS-008030-3-N

UNIT:  
mm

SCALE:  
A4 3:1

FINISH:

MATERIAL:  
RoHS Compliant

THIRD ANGLE  
PROJECTION

TOLERANCE: Angle:± 1°  
X,± 0.15 .XX± 0.05

DRAWN:  
Sheng

SHEET:  
2/2

REV.  
E

CHECKED:  
Gary Kang

APPROVED:  
George Yang

DATE:  
09/10/2014